

KEBATRON PPS C1065X1

PPS-(GF+MD)65

Barlog plastics GmbH

| Processing/Physical Characteristics | Value | Unit | Test Standard |
|-------------------------------------|-------|------|-----------------|
| ISO Data | | | |
| Molding shrinkage, parallel | 0.2 | % | ISO 294-4, 2577 |
| Molding shrinkage, normal | 0.6 | % | ISO 294-4, 2577 |

| Mechanical properties | Value | Unit | Test Standard |
|---------------------------------------|-------|-------------------|---------------|
| ISO Data | | | |
| Tensile Modulus | 22000 | MPa | ISO 527 |
| Stress at break | 130 | MPa | ISO 527 |
| Strain at break | 0.8 | % | ISO 527 |
| Charpy impact strength, +23°C | 18 | kJ/m ² | ISO 179/1eU |
| Charpy notched impact strength, +23°C | 8 | kJ/m ² | ISO 179/1eA |

| Thermal properties | Value | Unit | Test Standard |
|---|-------|-------|-----------------|
| ISO Data | | | |
| Melting temperature, 10°C/min | 278 | °C | ISO 11357-1/-3 |
| Temp. of deflection under load, 1.80 MPa | 260 | °C | ISO 75-1/-2 |
| Coeff. of linear therm. expansion, parallel | 17 | E-6/K | ISO 11359-1/-2 |
| Coeff. of linear therm. expansion, normal | 24 | E-6/K | ISO 11359-1/-2 |
| Burning behav. at thickness h | V-0 | class | IEC 60695-11-10 |
| Thickness tested | 0.4 | mm | - |

| Electrical properties | Value | Unit | Test Standard |
|-----------------------|-------|-------|---------------|
| ISO Data | | | |
| Volume resistivity | 1E14 | Ohm*m | IEC 62631-3-1 |

| Other properties | Value | Unit | Test Standard |
|------------------|-------|-------------------|----------------|
| Water absorption | 0.02 | % | Sim. to ISO 62 |
| Density | 1970 | kg/m ³ | ISO 1183 |

| Processing Recommendation Injection Molding | Value | Unit | Test Standard |
|---|-----------|------|---------------|
| Pre-drying - Temperature | 120 - 140 | °C | - |
| Pre-drying - Time | 4 - 8 | h | - |
| Processing humidity | ≤0.02 | % | - |
| Melt temperature | 320 - 340 | °C | - |
| Mold temperature | 140 - 180 | °C | - |
| Back pressure | <1 | MPa | - |

Characteristics**Processing**

Injection Molding

Special Characteristics

Heat stabilized or stable to heat

Features

Low Warpage

Applications

Aircraft and Aerospace, Automotive, Electrical and Electrical, Encapsulation

Regional Availability

Europe